

### **General Description**

The AAT7361 is a low threshold dual P-channel MOSFET designed for the battery, cell phone, and PDA markets. Using AnalogicTech's ultra-high-density MOSFET process and space-saving, small-outline, J-lead package, performance superior to that normally found in a larger footprint has been squeezed into the footprint of a TSOPJW8 package.

### **Applications**

- Battery Packs
- Battery-Powered Portable Equipment
- Cellular and Cordless Telephones

### **Absolute Maximum Ratings**

 $T_A = 25^{\circ}C$ , unless otherwise noted.

Symbol	Description	Value	Units		
V <sub>DS</sub>	Drain-Source Voltage		-20	V	
V <sub>GS</sub>	Gate-Source Voltage		±12	v	
1	Continuous Drain Current @ T <sub>J</sub> = 150°C <sup>1</sup>	$T_A = 25^{\circ}C$	±3.0		
I <sub>D</sub>		$T_A = 70^{\circ}C$	±2.4	А	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	±9	A		
I <sub>S</sub>	Continuous Source Current (Source-Drain Diode) <sup>1</sup>	-1.0			
TJ	Operating Junction Temperature Range	-55 to 150	°C		
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C		

### **Thermal Characteristics**<sup>1</sup>

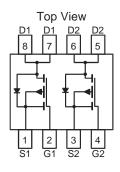
Symbol	Description		Тур	Мах	Units	
R <sub>θJA</sub>	Junction-to-Ambient Steady State, One FET On		124	155	°C/W	
R <sub>0JA2</sub>	Junction-to-Ambient t<5 Seconds		74	90	°C/W	
R <sub>θJF</sub>	Junction-to-Foot		66	80	°C/W	
р	P <sub>D</sub> Maximum Power Dissipation	T <sub>A</sub> = 25°C	1.4		W	
ΓD		$T_A = 70^{\circ}C$	0.9		vv	

1. Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5-second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications.  $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$  where the foot thermal reference is defined as the normal solder mounting surface of the device's leads.  $R_{\theta JF}$  is guaranteed by design; however,  $R_{\theta CA}$  is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

2. Pulse test: Pulse Width = 300µs.

- Drain-Source Voltage (max): -20V
- Continuous Drain Current<sup>1</sup> (max) -3.0A @ 25°C
- Low On-Resistance:
  - 100mΩ @ V<sub>GS</sub> = -4.5V
  - 175m $\Omega @ V_{GS} = -2.5V$

### **Dual TSOPJW-8 Package**





### AAT7361 20V P-Channel Power MOSFET

# **Electrical Characteristics**

 $T_{\rm J} = 25^{\circ}$ C, unless otherwise noted.

Symbol	Description	Conditions	Min	Тур	Max	Units			
DC Charao	DC Characteristics								
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_{D} = -250\mu A$	-20			V			
R <sub>DS(ON)</sub>	Drain-Source On-Resistance <sup>1</sup>	$V_{GS} = -4.5V, I_{D} = -3.0A$		80	100	mΩ			
		$V_{GS} = -2.5V, I_{D} = -2.3A$		140	175				
I <sub>D(ON)</sub>	On-State Drain Current <sup>1</sup>	$V_{GS}$ = -4.5V, $V_{DS}$ = -5V (pulsed)	-9			А			
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250 \mu A$	-0.6			V			
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{GS} = \pm 12V, V_{DS} = 0V$			±100	nA			
1	Drain Source Leakage Current	$V_{GS} = 0V, V_{DS} = -20V$			-1				
I <sub>DSS</sub>		$V_{GS} = 0V, V_{DS} = -16V, T_{J} = 70^{\circ}C^{2}$			-5	μA			
9 <sub>fs</sub>	Forward Transconductance <sup>1</sup>	$V_{DS} = -5V, I_{D} = -3.0A$		5		S			
Dynamic (	Characteristics <sup>2</sup>								
Q <sub>G</sub>	Total Gate Charge	$V_{DS} = -10V, R_{D} = 3.3\Omega, V_{GS} = -4.5V$		6					
Q <sub>GS</sub>	Gate-Source Charge	$V_{DS} = -10V, R_{D} = 3.3\Omega, V_{GS} = -4.5V$		1.3		nC			
$Q_{GD}$	Gate-Drain Charge	$V_{DS} = -10V, R_{D} = 3.3\Omega, V_{GS} = -4.5V$		1.7					
t <sub>D(ON)</sub>	Turn-On Delay	$V_{DS}$ = -10V, $R_D$ = 3.3 $\Omega$ , $V_{GS}$ = -4.5V, $R_G$ = 6 $\Omega$		7					
t <sub>R</sub>	Turn-On Rise Time	$V_{DS}$ = -10V, $R_D$ = 3.3 $\Omega$ , $V_{GS}$ = -4.5V, $R_G$ = 6 $\Omega$		13		ns			
t <sub>D(OFF)</sub>	Turn-Off Delay	$V_{DS} = -10V, R_{D} = 3.3\Omega, V_{GS} = -4.5V, R_{G} = 6\Omega$		15					
t <sub>F</sub>	Turn-Off Fall Time	$V_{DS}$ = -10V, $R_D$ = 3.3 $\Omega$ , $V_{GS}$ = -4.5V, $R_G$ = 6 $\Omega$		20					
Source-Dr	Source-Drain Diode Characteristics								
$V_{SD}$	Source-Drain Forward Voltage <sup>1</sup>	$V_{GS} = 0, I_{S} = -3.0A$			-1.3	V			
ا <sub>s</sub>	Continuous Diode Current <sup>3</sup>				-1.0	А			

1. Pulse test: Pulse Width = 300µs.

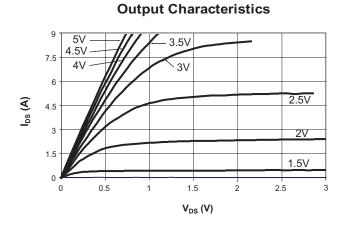
2. Guaranteed by design. Not subject to production testing.

<sup>3.</sup> Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5-second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications.  $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$  where the foot thermal reference is defined as the normal solder mounting surface of the device's leads.  $R_{\theta JF}$  is guaranteed by design; however,  $R_{\theta CA}$  is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

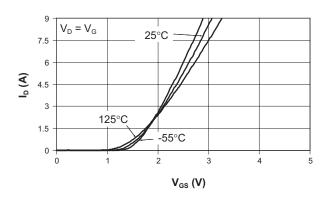


### **Typical Characteristics**

 $T_J = 25^{\circ}C$ , unless otherwise noted.



**Transfer Characteristics** 



**On-Resistance vs. Drain Current** 



0.4

0.32

0.24

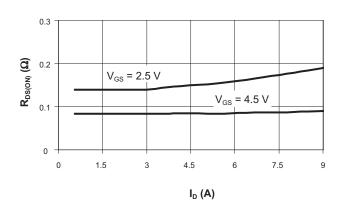
0.16

0.08

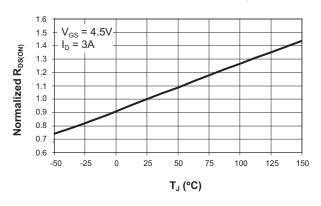
0 + 0

 $R_{DS(ON)}$  ( $\Omega$ )

I<sub>D</sub> = 3A



**On-Resistance vs. Junction Temperature** 



V<sub>GS</sub> (V)

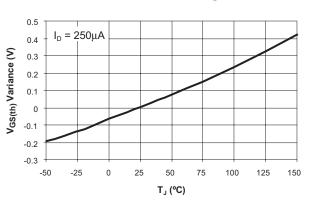
3

4

5

2

1



**Threshold Voltage** 



## AAT7361 20V P-Channel Power MOSFET

### **Typical Characteristics**

 $T_J = 25^{\circ}C$ , unless otherwise noted.

700

600

500

400

300

200

100

0 -

0

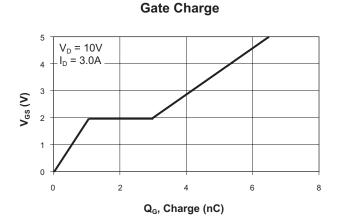
Ciss

C

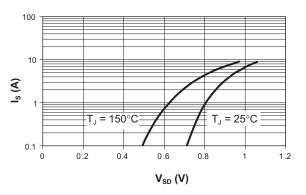
 $C_{rss}$ 

5

Capacitance (pF)



Source-Drain Diode Forward Voltage



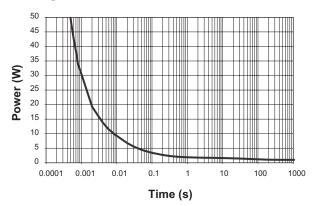
Capacitance

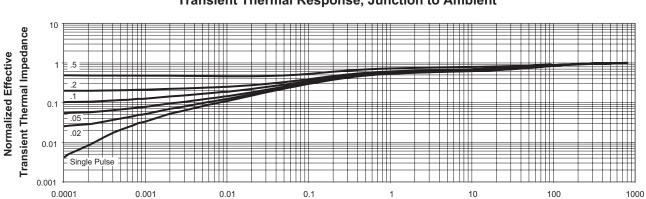
10

V<sub>DS</sub> (V)

15

Single Pulse Power, Junction To Ambient







20

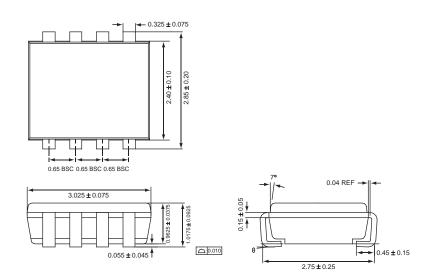


# **Ordering Information**

Package	<b>Marking</b> <sup>1</sup>	Part Number (Tape and Reel) <sup>2</sup>
TSOPJW-8	JYXYY	AAT7361ITS-T1

## Package Information

**TSOPJW-8** 



All dimensions in millimeters.

<sup>1.</sup> XYY = assembly and date code.

<sup>2.</sup> Sample stock is generally held on part numbers listed in BOLD.



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